



August 7, 2026

NEWS RELEASE

Enhanced Production Capacity for MicroThin™

**- Investing a total of 30 billion yen through 2030 to increase production capacity
1.6 times to 8 million m² per month -**

Mitsui Kinzoku Company, Limited (President: Seiji Ikenobu; “Mitsui Kinzoku”) announces that it will expand production capacity for MicroThin™, which is manufactured at its Ageo Plant and Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn Bhd). In a news release dated January 7, 2025 (“Mitsui Kinzoku Plans to Increase MicroThin™ Production Capacity”), Mitsui Kinzoku announced information about its production plans beyond 2028, with the aim of increasing total monthly production capacity to 5.6 million m² by FY2030. By bringing these plans forward, Mitsui Kinzoku now intends to reach production capacity of 6 million m² per month during FY2028, and expand capacity to 8 million m² per month during FY2030 by making additional investments. We expect the amount invested to total around 30 billion yen.

MicroThin™, carrier-supported ultra-thin copper foil, is a product of Mitsui Kinzoku combining a copper foil thickness ranging from 1.5 μm to 5 μm suitable for forming fine circuits, with multiple types of fine-roughening treatment. It is mainly used for IC substrate, optical modules, and motherboards for smartphones (HDI printed circuit boards).

Demand for IC substrate has grown significantly due to their increasing application in data centers and memories, and their use in optical modules and AI servers. Demand will continue to increase in the future because of their increased use for new applications such as multilayer PCBs for optical modules and ultra-high speed infrastructure and flexible PCBs for ultra-high-speed communication devices.

The Company will contribute to the realization of a sustainable society by implementing its vision for 2030, “Building new businesses — and the future — with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

■ MicroThin™ production capacity (Unit: 10,000 m² / month) (for reference)

	FY2025	FY2026	FY2027	FY2028	FY2030
Ageo Plant	250	250	260	280	* Under consideration
Malaysia Plant	240	240	260	320	* Under consideration
Total	490	490	520	600	800

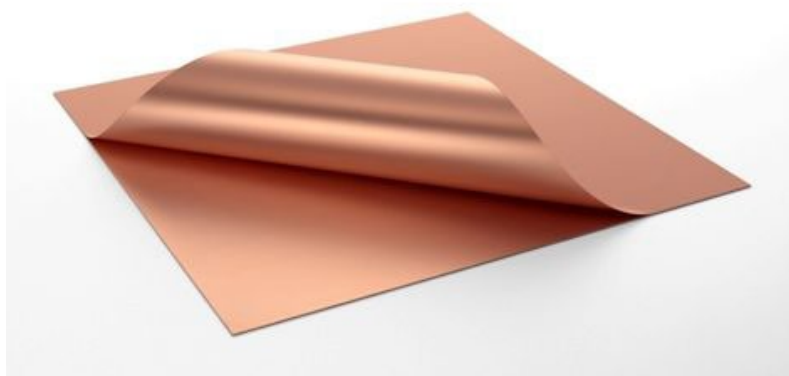
* At this stage, the decision has been made to expand production capacity. Final decisions on the scale of investment, locations to be invested in and other details will be made in light of customer demand, the market environment, various support programs and other factors.

[Contact]

Corporate Communications Department, Corporate Planning & Control Sector, Mitsui Kinzoku Company, Limited

TEL: +81-3-5437-8028 Email: PR@mitsui-kinzoku.com

Picture of MicroThin™



Top: Copper carrier foil (thickness: 18μm or 12μm)

Bottom: Extremely-thin copper foil (thickness: 1.5μm to 5μm)